



November 7, 2013

Pedro Shioga
Labmat UFSC
Mechanical Engineering
Rua Delfino Conti, s/n. Bloco B - Engenharia Mecânica - UFSC
Campus Trindade
Florianopolis, 88040-370
BRAZIL

Dear Mr. Shioga,

The Student Sponsorship Committee of the Society of Vacuum Coaters has evaluated applications for support to attend the 2014 Technical Conference in Chicago, Illinois.

After detailed analysis of the supplied documents and high quality project presentations, I have the pleasure to inform you that your application has been accepted. As a result, you will receive the following benefits:

- Your registration fee for the SVC TechCon is waived
- SVC covers your hotel expenses for up to 5 nights – *double occupancy*
- SVC contributes up to \$1,000 for your airfare and air travel insurance. The purchase of air travel insurance is required.

This support is contingent on your agreement to give an oral presentation at the TechCon and submission of a manuscript for the SVC Proceedings. Regarding the publication, you will receive specific guidelines shortly.

I congratulate you on this award and encourage you to benefit from this unique opportunity to present your work and establish and promote contacts with the SVC community. We all believe that this may be of particular interest for the progress of your career, for which I wish you great success.

Best Regards,

A handwritten signature in black ink, appearing to read 'Hana Baránková', written over a horizontal line.

Hana Baránková
Professor, Uppsala University
Chair, SVC Student Sponsorship Committee

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